



PRODUCT SPECIFICATION

FG6221ASRC-0L

Wi-Fi Dual-band 1x1 11ac + Bluetooth 4.2

Combo Module

Version:v2.3

Customer: _____

Customer P/N: _____

Signature: _____

Date: _____

Office: 14th floor, Block B, phoenix zhigu, Xixiang Street, Baoan District, Shenzhen

Factory: NO.8, Litong RD., Liuyang Economic & Technical Development Zone, Changsha, CHINA

TEL:+86-755-2955-8186

Website:www.fn-link.com

FG6221ASRC -0L Module Datasheet

Ordering Information	Part NO.	Description
	FG6221ASRC-0L	RTL8821CS-CG, a/b/g/n/ac, Wi-Fi+BT4.2, 1T1R, 12X12mm, SDIO +Uart, PCB V1.0 (no C33)
	FG6221ASRC-KL	RTL8821CS-CG, a/b/g/n/ac, Wi-Fi+BT4.2, 1T1R, 12X12mm, SDIO +Uart, PCB V1.0 (no C33)(客供 IC)

Target power

2.4G: 16/15/14

5.8G: 13/12/10

CONTENTS

1. General Description	5
1.1 Introduction	5
1.2 Description	5
2. Features	6
3. Block Diagram	6
4. General Specification	7
4.1 2.4GHz WI-FI Specification	7
4.2 5GHz WI-FI Specification	8
4.3 Bluetooth Specification	11
5. ID setting information	12
6. Pin Definition	12
6.1 Pin Outline	12
6.2 Pin Definition details	13
7. Electrical Specifications	14
7.1 Recommended Operating Rating	14
7.2 Interface Circuit time series	15
7.2.1 SDIO Pin Description	15
7.2.2 SDIO Timing Diagram	15
7.3 System Power Sequence	16
7.3.1 System Power On Sequence	16
8. Size reference	17
8.1 Module Picture	17
8.2 Marking Description	17
8.3 Physical Dimensions	18
8.4 Layout Recommendation	19
9. The Key Material List	20
10. Reference Design	20
11. Recommended Reflow Profile	21
12. RoHS compliance	21
13. Package	22
13.1 Reel	22
13.2 Carrier Tape Detail	22
13.3 Packaging Detail	23
13.4 Tray	24
14. Moisture sensitivity	24
15. FCC & I C warning message	25
- 26	

[illegible]

1. General Description

1.1 Introduction

Fn-Link Technology would like to announce a low-cost and low-power consumption module which has all of the Wi-Fi functionalities. It is a highly-integrated IEEE 802.11 a/b/g/n/ac MAC/Baseband/RF WLAN single chip. For Wireless LAN(WLAN)operation. The integrated module provides SDIO interface for Wi-Fi . The module provides simple legacy and 20MHz/40MHz/80MHz co-existence mechanisms to ensure backward and network compatibility

The wireless module complies with IEEE 802.11 a/b/g/n/ac standard and it can achieve up to a speed of 433.3Mbps with single stream in 802.11ac draft to connect to the wireless LAN. The integrated module provides SDIO interface for Wi-Fi, UART / PCM interface for Bluetooth.

This compact module is a total solution for a combination of Wi-Fi + BT technologies.

The module is specifically developed for Smart phones and Portable devices.

1.2 Description

Model Name	6221ASRC
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x T: 12 x 12 x 2.0 (typical) mm
Wi-Fi Interface	Support SDIO V3.0/2.0/1.1
BT Interface	UART / PCM
OS supported	Android /Linux/ Win CE /iOS /XP/WIN7/WIN10
Operating temperature	0°C to 70°C
Storage temperature	-40°C to 85°C

2. Features

General

- Highly integrated wireless local area network(WLAN) system-on-chip (SOC) for 5 GHZ 802.11ac, or 2.4G/5G 802.11n WLAN applications
- Supports 20/40MHz at 2.4GHz and supports 20/40/80MHz at 5GHz
- Supports Bluetooth for class1 and class2 power level transmissions without requiring an external PA

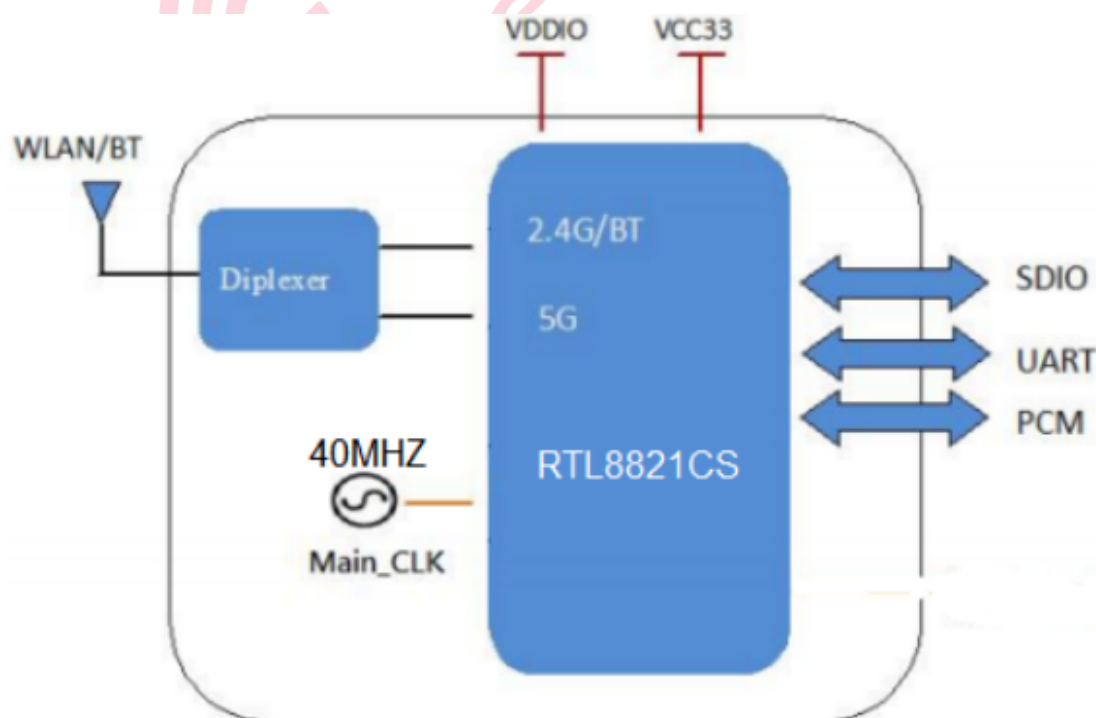
Host Interface

- Supports low power SDIO3.0 interface for WLAN and UART/PCM interface for Bluetooth

Bluetooth Features

- Supports WLAN-Bluetooth coexistence
- Supports Bluetooth V4.2+HS, BLE and be backwards compatible with Bluetooth 1.2, 2.X+ enhance data rate.
- BT host digital interface:
 - HCI UART (up to 4 Mbps)
 - PCM for audio data

3. Block Diagram



4. General Specification

4.1 2.4GHz WI-FI Specification

Feature	Description	
WLAN Standard	IEEE 802.11 b/g/n Wi-Fi compliant	
Frequency Range	2.400 GHz ~ 2.4835 GHz (2.4 GHz ISM Band)	
Number of Channels	2.4GHz: Ch1 ~ Ch14	
Modulation	DBPSK/DQPSK/CCK(DSSS)、BPSK/QPSK/16QAM/64QAM(OF DM)	
Test Items	Typical Value	EVM
Output Power ¹	802.11b /11Mbps : 16dBm ± 1.5 dB	EVM ≤ -9dB
	802.11g /54Mbps : 15dBm ± 1.5 dB	EVM ≤ -25dB
	802.11n /MCS7(HT 20): 14dBm ± 1.5 dB	EVM ≤ -28dB
	802.11n /MCS7(HT 40): 14 dBm ± 1.5 dB	EVM ≤ -28dB
Spectrum Mask	Meet with IEEE standard	
Freq. Tolerance	± 20ppm	
Receive Sensitivity (11b,20MHz) @8% PER	- 1Mbps PER @ -94 dBm	≤-83
	- 2Mbps PER @ -88 dBm	≤-80
	- 5.5Mbps PER @ -86 dBm	≤-79
	- 11Mbps PER @ -85 dBm	≤-76
Receive Sensitivity (11g,20MHz) @10% PER	- 6Mbps PER @ -88 dBm	≤-85
	- 9Mbps PER @ -86 dBm	≤-84
	- 12Mbps PER @ -85 dBm	≤-82
	- 18Mbps PER @ -83 dBm	≤-80
	- 24Mbps PER @ -81 dBm	≤-77
	- 36Mbps PER @ -78 dBm	≤-73
	- 48Mbps PER @ -74 dBm	≤-69
	- 54Mbps PER @ -72 dBm	≤-68
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0 PER @ -87 dBm	≤-85
	- MCS=1 PER @ -83 dBm	≤-82
	- MCS=2 PER @ -82 dBm	≤-80
	- MCS=3 PER @ -78 dBm	≤-77
	- MCS=4 PER @ -75 dBm	≤-73
	- MCS=5 PER @ -73 dBm	≤-69
	- MCS=6 PER @ -70 dBm	≤-68
	- MCS=7 PER @ -69 dBm	≤-67
Receive Sensitivity	- MCS=0 PER @ -87 dBm	≤-82

(11n,40MHz) @10% PER	- MCS=1	PER @ -83 dBm	≤-79
	- MCS=2	PER @ -82 dBm	≤-77
	- MCS=3	PER @ -78 dBm	≤-74
	- MCS=4	PER @ -74 dBm	≤-70
	- MCS=5	PER @ -70 dBm	≤-66
	- MCS=6	PER @ -68 dBm	≤-65
	- MCS=7	PER @ -67 dBm	≤-64

4.2 5GHz WI-FI Specification

Feature	Description	
WLAN Standard	IEEE 802.11a/n/ac, Wi-Fi compliant	
Frequency Range	5.150 GHz ~ 5.850 GHz (5.0 GHz ISM Band)	
Number of Channels	5.0GHz: Please see the table1	
Modulation	802.11a/n : 64-QAM,16-QAM, QPSK, BPSK 802.11ac : 256-QAM, 64-QAM,16-QAM, QPSK, BPSK	
Test Items	Typical Value	EVM
Output Power ²	802.11a /54Mbps : 13 dBm ± 1.5 dB	EVM ≤ -25dB
	802.11n /MCS7(HT20) : 12 dBm ± 1.5 dB	EVM ≤ -28dB
	802.11n /MCS7(HT40) : 12 dBm ± 1.5 dB	EVM ≤ -28dB
	802.11ac/MCS8(VHT20) : 11 dBm ± 1.5 dB	EVM ≤ -30dB
	802.11ac/MCS7(VHT40) : 12 dBm ± 1.5 dB	EVM ≤ -30dB
	802.11ac/MCS9(VHT40) : 10 dBm ± 1.5 dB	EVM ≤ -32dB
	802.11ac/MCS9(VHT80) : 10 dBm ± 1.5 dB	EVM ≤ -32dB
Test Items	Typical Value	Standard Value
Receive Sensitivity (11a,20MHz) @10% PER	- 6Mbps PER @ -87 dBm	≤-82
	- 9Mbps PER @ -85 dBm	≤-81
	- 12Mbps PER @ -84 dBm	≤-79
	- 18Mbps PER @ -82 dBm	≤-77
	- 24Mbps PER @ -78 dBm	≤-74
	- 36Mbps PER @ -75 dBm	≤-70
	- 48Mbps PER @ -70 dBm	≤-66
	- 54Mbps PER @ -69 dBm	≤-65
Receive Sensitivity	- MCS=0 PER @ -85 dBm	≤-82

(11n,20MHz) @10% PER	- MCS=1	PER @ -83 dBm	≤-79
	- MCS=2	PER @ -80 dBm	≤-77
	- MCS=3	PER @ -77 dBm	≤-74
	- MCS=4	PER @ -73 dBm	≤-70
	- MCS=5	PER @ -69 dBm	≤-66
	- MCS=6	PER @ -67 dBm	≤-65
	- MCS=7	PER @ -66 dBm	≤-64
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0	PER @ -82 dBm	≤-81
	- MCS=1	PER @ -79 dBm	≤-78
	- MCS=2	PER @ -78 dBm	≤-76
	- MCS=3	PER @ -73 dBm	≤-72
	- MCS=4	PER @ -70 dBm	≤-69
	- MCS=5	PER @ -65 dBm	≤-64
	- MCS=6	PER @ -64 dBm	≤-63
Receive Sensitivity (11ac,20MHz)@10% PER	- MCS=7	PER @ -62 dBm	≤-61
	- MCS=0	PER @ -86 dBm	≤-82
	- MCS=1	PER @ -84 dBm	≤-81
	- MCS=2	PER @ -81 dBm	≤-79
	- MCS=3	PER @ -78 dBm	≤-74
	- MCS=4	PER @ -74 dBm	≤-71
	- MCS=5	PER @ -70 dBm	≤-67
	- MCS=6	PER @ -68 dBm	≤-66
	- MCS=7	PER @ -67 dBm	≤-61
Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=8	PER @ -63 dBm	≤-59
	- MCS=0	PER @ -82 dBm	≤-79
	- MCS=1	PER @ -78 dBm	≤-76
	- MCS=2	PER @ -76 dBm	≤-73
	- MCS=3	PER @ -73 dBm	≤-69
	- MCS=4	PER @ -70 dBm	≤-68
	- MCS=5	PER @ -65 dBm	≤-64
	- MCS=6	PER @ -63 dBm	≤-63
	- MCS=7	PER @ -61 dBm	≤-58
	- MCS=8	PER @ -59 dBm	≤-56
Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=9	PER @ -58 dBm	≤-54
	- MCS=0	PER @ -78 dBm	≤-76
	- MCS=1	PER @ -75 dBm	≤-73
	- MCS=2	PER @ -73 dBm	≤-71

- MCS=3	PER @ -69 dBm	≤-68
- MCS=4	PER @ -66 dBm	≤-64
- MCS=5	PER @ -64 dBm	≤-60
- MCS=6	PER @ -60 dBm	≤-59
- MCS=7	PER @ -58 dBm	≤-58
- MCS=8	PER @ -55 dBm	≤-53
- MCS=9	PER @ -54 dBm	≤-51

NOTES:1.Module have calibrated MCS7 HT40 rate power,other rates control by driver;

2.Module have calibrated MCS7 HT40 /11M rate power, other rats control by driver;

15GHz Channel table

Band (GHz)	Operating Channel Numbers	Channel center frequencies(MHz)
5150MHz~5250MHz	36	5180
	40	5200
	44	5220
	48	5240
5250MHz~5350MHz	52	5260
	56	5280
	60	5300
	64	5320
5470MHz~5725MHz	100	5500
	104	5520
	108	5540
	112	5560
	116	5580
	120	5600
	124	5620
	128	5640
	132	5660
	136	5680
5725MHz~5850MHz	140	5700
	149	5745
	153	5765
	157	5785
	161	5805
	165	5825

4.3 Bluetooth Specification

Feature	Description
General Specification	
Bluetooth Standard	BDR,EDR(1Mbps & 2Mbps & 3Mbps),LE(1Mbps)
Host Interface	UART
Frequency Band	2400 MHz ~ 2483.5 MHz
Number of Channels	79 channels for classic,40 channels for BLE
Modulation	GFSK, $\pi/4$ -DQPSK,8DPSK
RF Specification	
Output Power , tolerance ± 3 dB	
	CL1(dBm)
BDR Output Power	5
EDR Output Power	5
BLE Output Power	5
Sensitivity, tolerance : /	
Sensitivity @ BER=0.1% for GFSK (1Mbps)	-85
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)	-85
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)	-85
Sensitivity @ BLE=30.8% for LE (1Mbps)	-85
Maximum Input Level	GFSK (1Mbps):-20dBm
	$\pi/4$ -DQPSK (2Mbps) :-20dBm
	8DPSK (3Mbps) :-20dBm

5. ID setting information

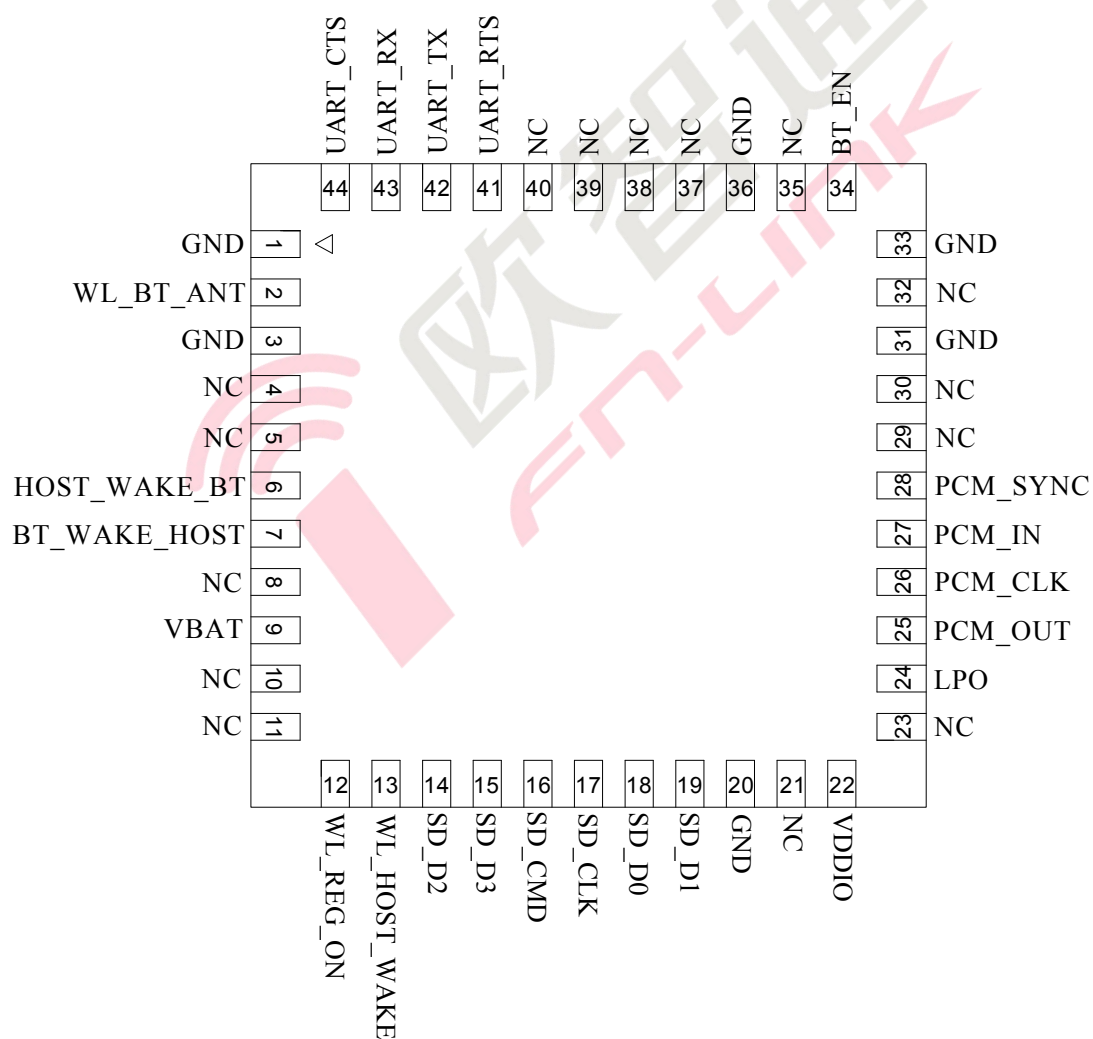
WI-FI

Vendor ID	024C
Product ID	C821

6. Pin Definition

6.1 Pin Outline

< TOP VIEW



6.2 Pin Definition details

NO.	Name	Type	Description	Voltage
1	GND	—	Ground connections	
2	WL_BT_ANT	I/O	RF I/O port	
3	GND	—	Ground connections	
4	NC	—	Floating (Don't connected to ground)	
5	NC	—	Floating (Don't connected to ground)	
6	HOST_WAKE_BT	I	HOST to wake-up Bluetooth device	VDDIO
7	BT_WAKE_HOST	O	Bluetooth device to wake-up HOST	VDDIO
8	NC	—	Floating (Don't connected to ground)	
9	VBAT	P	Main power voltage source input 3.3V	3.3V
10	NC	—	Floating (Don't connected to ground)	
11	NC	—	Floating (Don't connected to ground)	
12	WL_REG_ON	I	Enable pin for WLAN device ON: pull high ; OFF: pull low	VDDIO
13	WL_HOST_WAKE	O	WLAN to wake-up HOST	VDDIO
14	SD_D2	I/O	SDIO data line 2	1.8V or 3.3V
15	SD_D3	I/O	SDIO data line 3	1.8V or 3.3V
16	SD_CMD	I/O	SDIO command line	1.8V or 3.3V
17	SD_CLK	I/O	SDIO clock line	1.8V or 3.3V
18	SD_D0	I/O	SDIO data line 0	1.8V or 3.3V
19	SD_D1	I/O	SDIO data line 1	1.8V or 3.3V
20	GND	—	Ground connections	
21	NC	—	Floating (Don't connected to ground)	
22	VDDIO	P	I/O Voltage supply input	1.8V or 3.3V
23	NC	—	Floating (Don't connected to ground)	
24	LPO	I	External Low Power Clock input (32.768KHz)	
25	PCM_OUT	O	PCM Data output	VDDIO
26	PCM_CLK	I/O	PCM clock	VDDIO
27	PCM_IN	I	PCM data input	VDDIO
28	PCM_SYNC	I/O	PCM sync signal	VDDIO
29	NC	—	Floating (Don't connected to ground)	
30	NC	—	Floating (Don't connected to ground)	
31	GND	—	Ground connections	
32	NC	—	Floating (Don't connected to ground)	

33	GND	—	Ground connections	
34	BT_EN	I	Enable pin for Bluetooth device ON: pull high ; OFF: pull low	VDDIO
35	NC	—	Floating (Don't connected to ground)	
36	GND	—	Ground connections	
37	NC	—	Floating (Don't connected to ground)	
38	NC	—	Floating (Don't connected to ground)	
39	NC	—	Floating (Don't connected to ground)	
40	NC	—	Floating (Don't connected to ground)	
41	UART_RTS	O	Bluetooth UART interface	1.8V or 3.3V
42	UART_TX	O	Bluetooth UART interface	1.8V or 3.3V
43	UART_RX	I	Bluetooth UART interface	1.8V or 3.3V
44	UART_CTS	I	Bluetooth UART interface	1.8V or 3.3V

P:POWER I:INPUT O:OUTPUT VDDIO:1.8V ~ 3.3V

7. Electrical Specifications

7.1 Recommended Operating Rating

		Min.	Typ.	Max.	Unit
Operating Temperature		0	25	70	deg.C
VCC33		3.0	3.3	3.6	V
VDDIO		1.7	1.8 or 3.3	3.6	V
Power Consumption		VCC33 = 3.3V(Unit:mA)			
	Wi-Fi on Mode	68			
	TX (2.4G HT20)	217			
	RX (2.4G HT20)	108			
	TX (5G HT40)	252			
	RX (5G HT40)	115			
	BT on	19			

7.2 Interface Circuit time series

7.2.1 SDIO Pin Description

The module supports SDIO version 3.0 .

SDIO Pin Description

SD 4-Bit Mode	
DATA0	Data Line 0
DATA1	Data Line 1 or Interrupt
DATA2	Data Line 2 or Read Wait
DATA3	Data Line 3
CLK	Clock
CMD	Command Line

7.2.2 SDIO Timing Diagram

For timing criteria, please check specification in “SD specification Part1 Physical Layer Specification Version 3.01”

7.3 System Power Sequence

7.3.1 System Power On Sequence

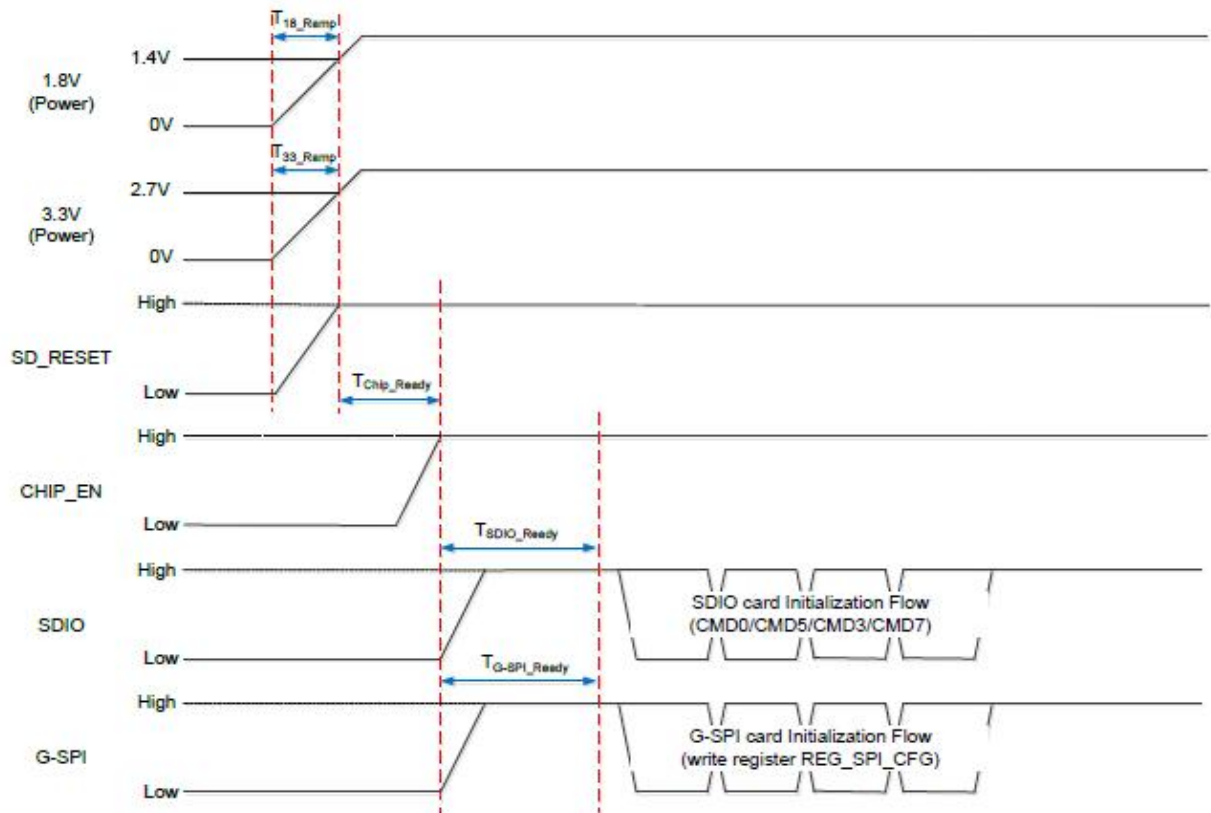


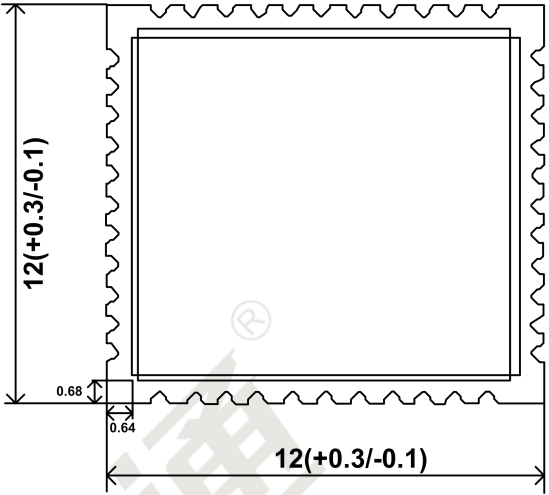
Figure 5. System Power-On Sequence

Table 18. System Power On Timing Parameters

	Min	Typical	Max	Unit	Description
T_{18_Ramp}	0.1	0.5	2.5	ms	The 1.8V main power ramp up duration.
T_{33_Ramp}	0.1	0.5	2.5	ms	The 3.3V main power ramp up duration.
T_{Chip_Ready}					CHIP_EN pull high timing
T_{SDIO_Ready}	1	2	10	ms	SDIO Not Ready Duration. In this state, the RTL8821CS-VI may respond to commands without the ready bit being set. After the ready bit is set, the host will initiate complete card detection procedure.
T_{G-SPI_Ready}	3	4	18	ms	The duration G-SPI device internal initialization. After T_{G-SPI_Ready} , SPI host can then send command to write
					REG_SPI_CFG register. REG_SPI_CFG register is to control G-SPI endian and word length.

8. Size reference

8.1 Module Picture

L x W : 12 x 12 (+0.3/-0.1) mm	
H: 2.0(±0.2) mm	
Weight	0.52g

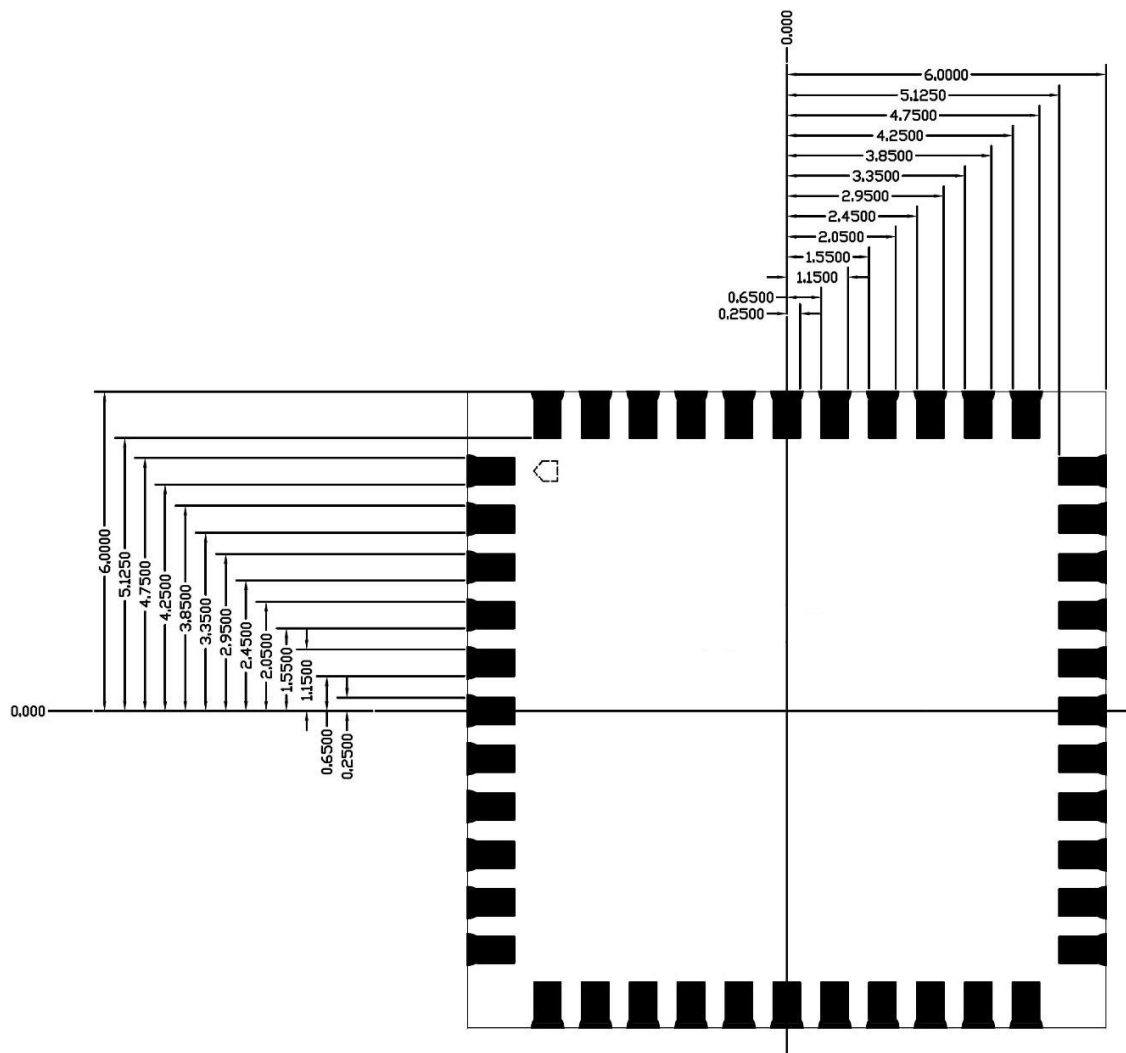
8.2 Marking Description

< TOP VIEW >

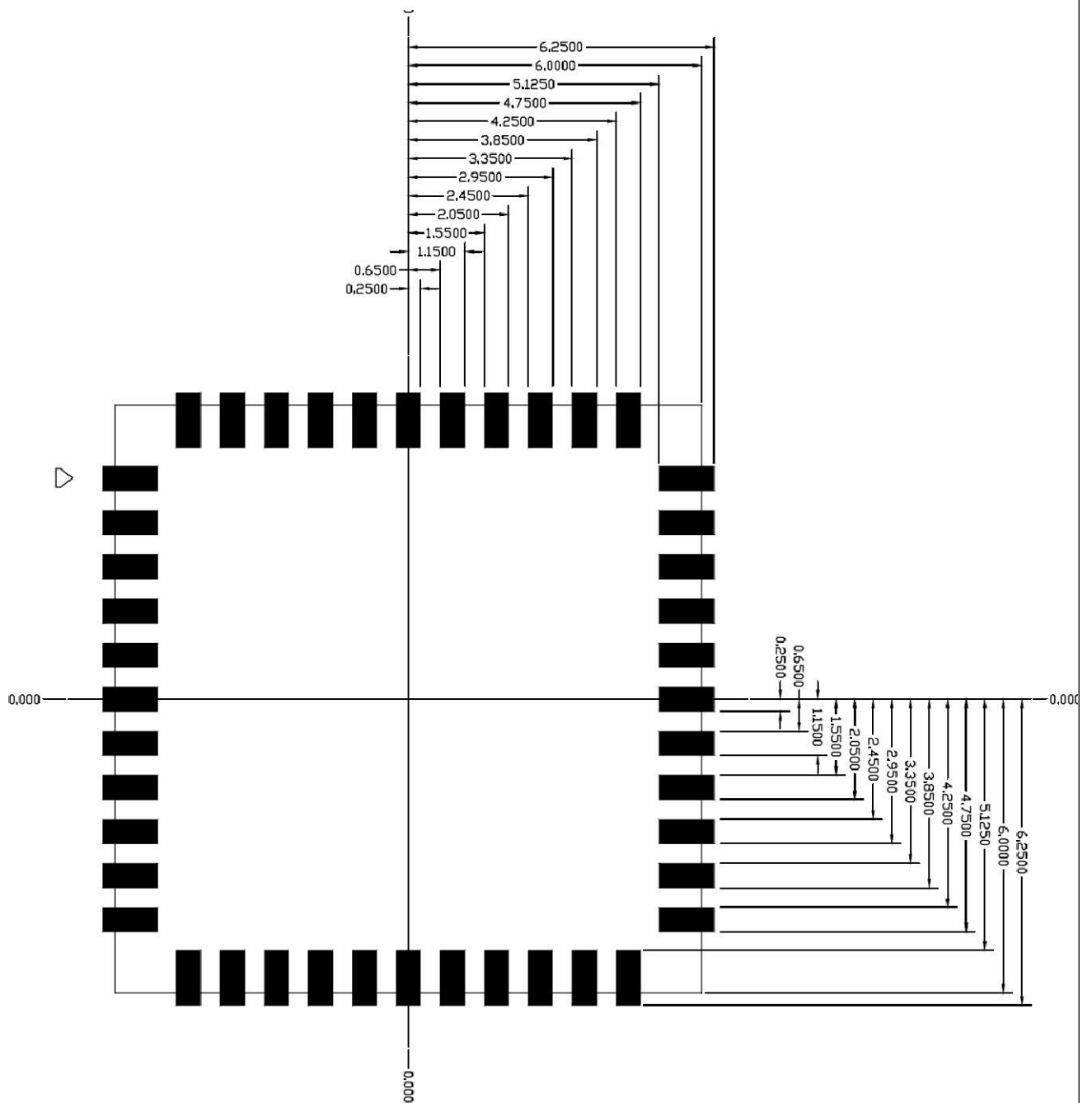


8.3 Physical Dimensions

<TOP View>



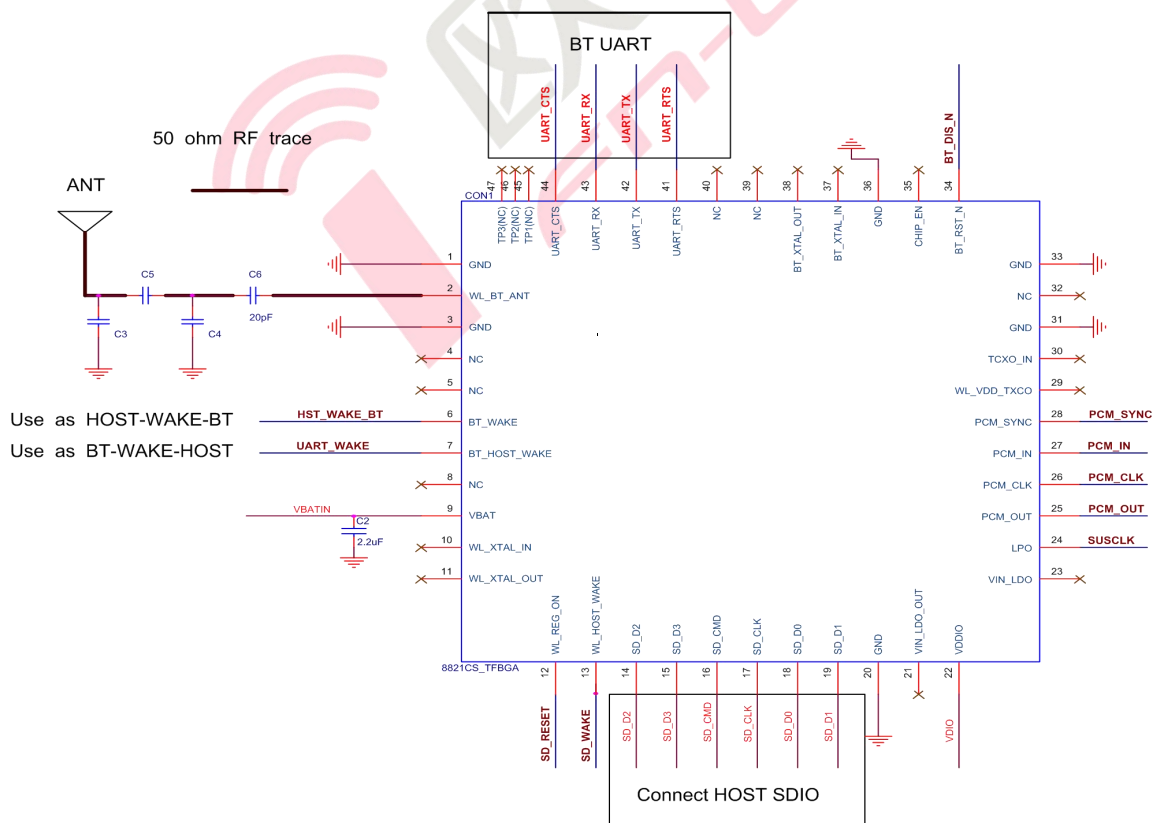
8.4 Layout Recommendation



9. The Key Material List

Inductor	2016,2.2UH,±20%,1200mA	Microgate, cenke, sunlord, ceaiya, GK, c hilisin
Shielding	6221A-SRC V2.0 Shield cover, copper	Suntech, JLitong, 卓益
diplexer	DP1005, 2.4G+5G, diplexer	ACX, Walsin, Murata, Glead, TDK
Crystal	40MHz, 2016, 15pF, 10ppm	Hosonic, ECEC, TKD, JWT
Chipset	RTL8821CS	Realtek
TVS	0201, 4V, 0.05pF ESD±15KV	muRata, Wayon, sunlord
PCB	6221A-SRC-V1.0, green, 4L, 12x12x0.5mm	Sunlord, kx-pcb, brainpower-pcb, truly, SL-pcb

10. Reference Design

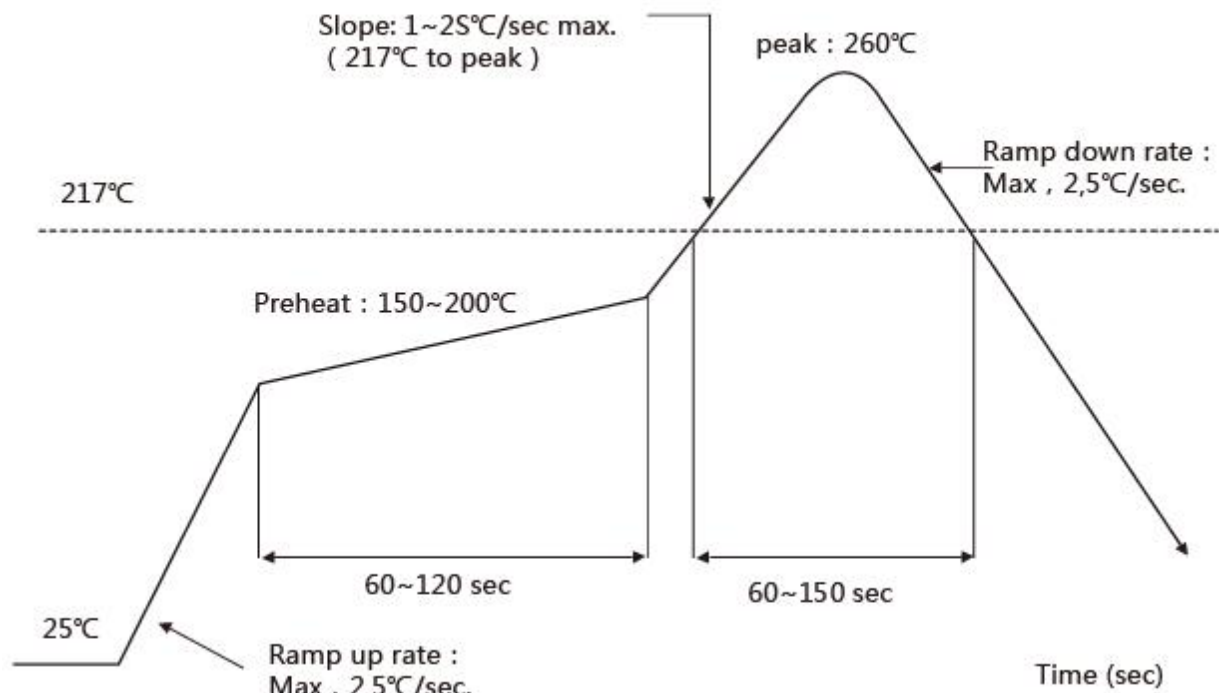


11. Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : $<260^{\circ}\text{C}$

Number of Times : ≤ 2 times



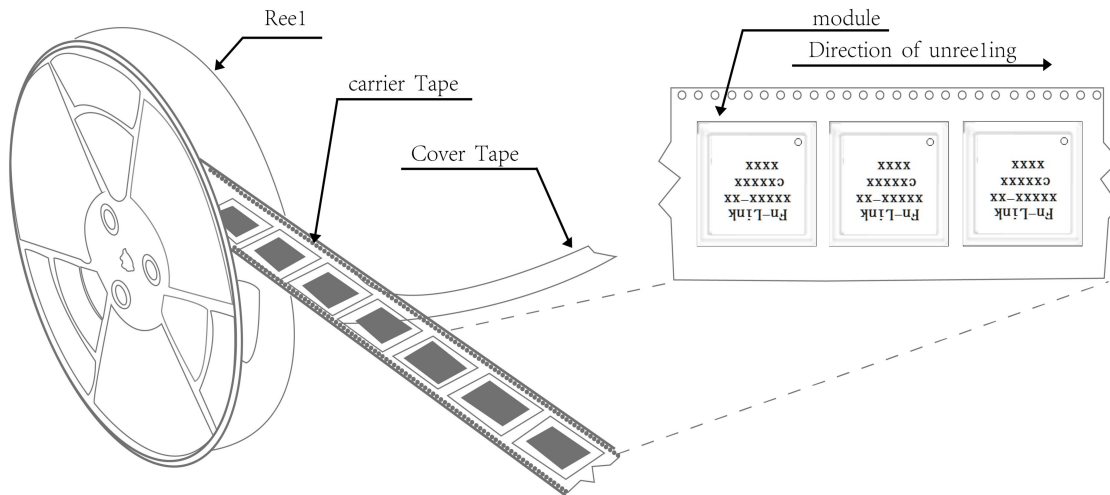
12. RoHS compliance

All hardware components are fully compliant with EU RoHS directive

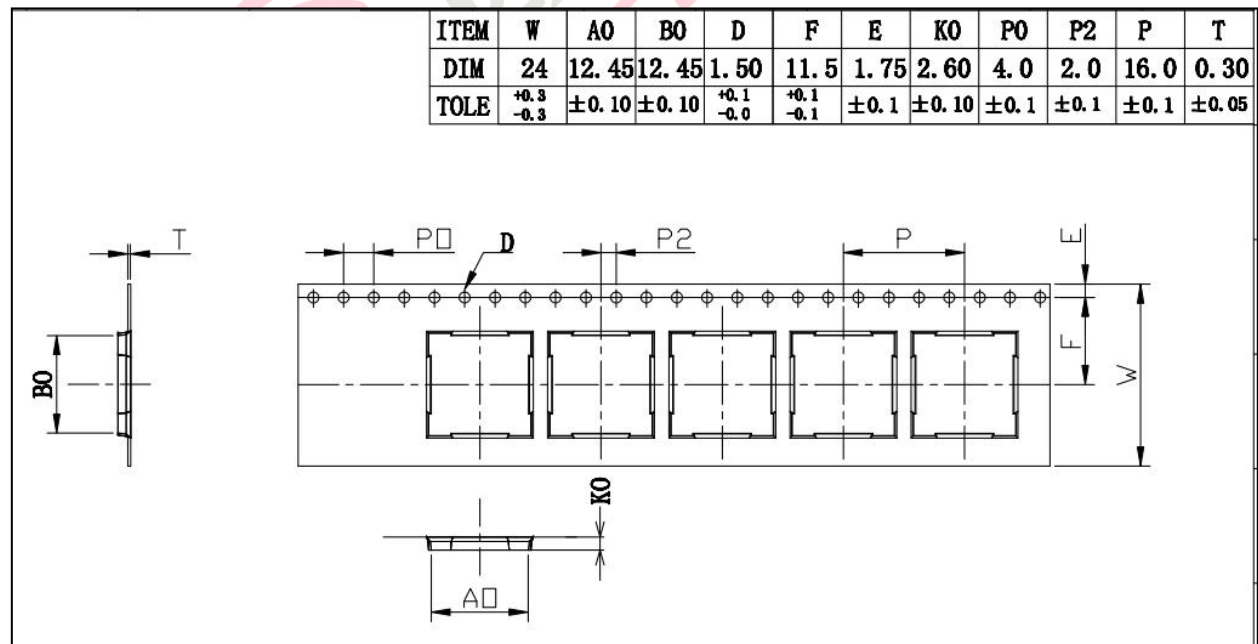
13. Package

13.1 Reel

A roll of 1500pcs



13.2 Carrier Tape Detail



13.3 Packaging Detail

the take-up package



Using self-adhesive tape

Size of black tape: 24mm*32.6m the cover tape :21.3mm*32.6m

Color of plastic disc: blue



NY bag size:460mm*385mm



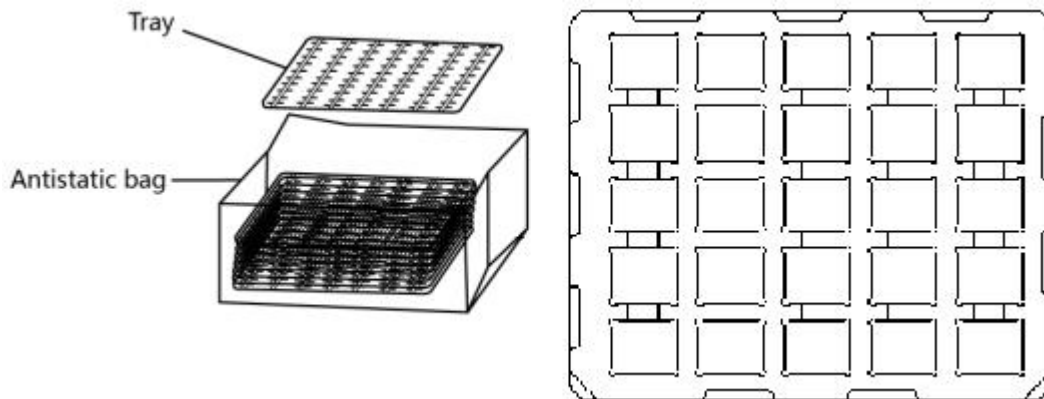
size : 350*350*35mm



The packing case size:350*210*370mm

13.4 Tray

Use pallet packaging for less than 300 pieces



14. Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care

all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- a) Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- b) Environmental condition during the production: 30°C / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5
- c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition b) "IPC/JEDEC J-STD-033A paragraph 5.2" is respected
- d) Baking is required if conditions b) or c) are not respected
- e) Baking is required if the humidity indicator inside the bag indicates 10% RH or more

15. FCC & IC warning message

FCC Statement

The Module is designed to comply with the FCC statement. FCC ID is 2AATL-6221ASRC. The host system using Module, should have label indicated it contain modular ' s FCC ID: 2AATL-6221ASRC. This radio module must not installed to collocate and operating simultaneously with other radios in host system additional testing and equipment authorization may be required to operating simultaneously with other radio. The Module and its antenna must not be co-located or operating in conjunction with any other transmitter or antenna within a host device.

The modular must be installed in the host that assign by Company name: FN-LINK TECHNOLOGY LIMITED, Model no.: FG6221ASRC-0L if other host types used would need further evaluation and possible C2PC if they are not significantly similar to the one tested The WIFI Module is designed for a compact PCB design. It should be installed and operated with host or other minimum distance of 20 centimeters between the radiator and your body." To comply with FCC regulations limiting both maximum RF output power and human exposure to RF radiation, the maximum antenna gain including cable loss in a mobile-only exposure condition must not exceed 2.19 dBi in the 2.4G band and 3.2 dBi in the 5G band. The module uses ceramic antenna interface and ping angle interface antenna, this antenna is sold with the module.

Notice to OEM integrator

The end user manual shall include all required regulatory information/warning as show in this manual. The OEM integrator is responsible for testing their end-product for any additional compliance requirements required with this module installed. If the final product contains circuits of other FCC PART 15 Subparts, the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed The intended use is generally not for the general public. It is generally for industry/commercial use. The connector is within the transmitter enclosure and can only be accessed by disassembly of the transmitter that is not normally required, the user has no access to the connector. Installation must be controlled. Installation requires special training.

This device complies with Part 15 of the FCC Rules.

This equipment should be installed and operated with a minimum distance of 20 cm between the radiator and your body.

Operations in the 5.15-5.35GHz band are restricted to indoors usage only.

ISED Statement

The Module is designed to comply with the ISED statement. IC is 12425A-6221ASRC. The host system using Module, should have label indicated it contain modular ' s IC: 12425A-6221ASRC. This radio module must not installed to collocate and operating simultaneously with other radios in host system additional testing and equipment authorization may be required to operating simultaneously with other radio. The Module and its antenna must not be co-located or operating in conjunction with any other transmitter or antenna within a host device.

The modular must be installed in the host that assign by Company name: FN-LINK TECHNOLOGY LIMITED, Model no.: FG6221ASRC-0L if other host types used would need further evaluation and possible C2PC if they are not significantly similar to the one tested The WIFI Module is designed for a compact PCB design. It should be installed and operated with host or other minimum distance of 20 centimeters between the radiator and your body." To comply with ISED regulations limiting both maximum RF output power and human exposure to RF radiation, the maximum antenna gain including cable loss in a mobile-only exposure condition must not exceed 2.19 dBi in the 2.4G band and 3.2dBi in the 5G band. The module uses ceramic antenna interface and ping angle interface antenna, this antenna is sold with the module.

This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada ' s licence-exempt RSS(s). Operation is subject to the following two conditions:

1. This device may not cause interference.
2. This device must accept any interference, including interference that may cause undesired operation of the device.

This equipment should be installed and operated with a minimum distance of 20 cm between the radiator and your body

Operations in the 5.15-5.35GHz band are restricted to indoors usage only.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Cet équipement doit être installé et utilisé avec une distance minimale de 20 cm entre le radiateur et votre corps

Le fonctionnement dans la bande 5,15 - 5,35 GHz est limité à un usage intérieur.